# SPECIFICATIONS FOR NICHIA UV LED

# MODEL: NSHU590B

NICHIA CORPORATION

(Ta=25°C)

#### **1.SPECIFICATIONS**

| (1 | ) Absolute Maximum Ratings |        |                         | (Ta=25°C) |
|----|----------------------------|--------|-------------------------|-----------|
|    | Item                       | Symbol | Absolute Maximum Rating | Unit      |
|    | Forward Current            | IF     | 25                      | mA        |
|    | Pulse Forward Current      | IFP    | 80                      | mA        |
|    | Allowable Reverse Current  | Ir     | 85                      | mA        |
|    | Power Dissipation          | Pd     | 100                     | mW        |
|    | Operating Temperature      | Topr   | -30 ~ + 85              | °C        |
|    | Storage Temperature        | Tstg   | -40 ~ +100              | °C        |
|    | Soldering Temperature      | Tsld   | 265°C for 10sec.        |           |

IFP Conditions : Pulse Width  $\leq 10$ msec. and Duty  $\leq 1/10$ 

#### (2) Initial Electrical/Optical Characteristics

| Item                 |         | Symbol             | Condition | Min. | Тур. | Max. | Unit |
|----------------------|---------|--------------------|-----------|------|------|------|------|
| Forward Voltage      |         | VF                 | IF=20[mA] | -    | 3.6  | 4.0  | V    |
| Peak Wavelength      | Rank Ua | λΡ                 | IF=20[mA] | 360  | 365  | 370  | nm   |
| Spectrum Half Width  |         | $	riangle \lambda$ | IF=20[mA] | -    | 10   | -    | nm   |
|                      | Rank 2  | Po                 | IF=20[mA] | 850  | 1000 | 1200 | μW   |
| Optical Power Output | Rank 3  | Po                 | IF=20[mA] | 1200 | 1400 | 1700 | μW   |
|                      | Rank 4  | Po                 | IF=20[mA] | 1700 | 2000 | 2400 | μW   |

\* Optical Power Output Measurement allowance is  $\pm 10\%$ .

**\*\*** Peak Wavelength Measurement allowance is ±3nm.

\*\*\* One delivery will include up to three different ranks of the products. The quantity-ratio of the three ranks is decided by Nichia.

# 2.TYPICAL INITIAL OPTICAL/ELECTRICAL CHARACTERISTICS Please refer to figure's page.

#### 3.OUTLINE DIMENSIONS AND MATERIALS

Please refer to figure's page.

| Material as follows | ; |
|---------------------|---|
|---------------------|---|

| Glass | : | Hard Glass |            |
|-------|---|------------|------------|
| Cap   | : | Ni Plating | Iron Alloy |
| Lead  | : | Au Plating | Iron Alloy |

### 4.PACKAGING

 $\cdot$  The LEDs are packed in cardboard boxes after packaging in anti-electrostatic bags. Please refer to figure's page.

The label on the minimum packing unit shows ; Part Number, Lot Number, Ranking, Quantity

 $\cdot$  In order to protect the LEDs from mechanical shock, we pack them in cardboard boxes for transportation.

- The LEDs may be damaged if the boxes are dropped or receive a strong impact against them, so precautions must be taken to prevent any damage.
- $\cdot$  The boxes are not water resistant and therefore must be kept away from water and moisture.
- · When the LEDs are transported, we recommend that you use the same packing method as Nichia.

### 5.LOT NUMBER

The first six digits number shows **lot number**.

The lot number is composed of the following characters;

 $\bigcirc \Box \times \times \times \times \cdot \bigtriangleup \blacksquare$ 

○ - Year (3 for 2003, 4 for 2004)

- $\Box$  Month (1 for Jan., 9 for Sep., A for Oct., B for Nov.)
- $\times \times \times \times$  Nichia's Product Number
  - $\triangle$  Ranking by Wavelength
  - Ranking by Optical Power Output

# **6.RELIABILITY** (1) TEST ITEMS AND RESULTS

|                             | Standard      |   |              | Number of |
|-----------------------------|---------------|---|--------------|-----------|
| Test Item                   | Test Method   | Test Conditions   | Note         | Damaged   |
| Resistance to               | JEITA ED-4701 | Tsld= $260 \pm 5^{\circ}$ C, 10sec.                     | 1 time       | 0/100     |
| Soldering Heat              | 300 302       | 3mm from the base of the lead                           |              |           |
| Solderability               | JEITA ED-4701 | Tsld= $235 \pm 5^{\circ}$ C, 5sec.                      | 1 time       | 0/100     |
|                             | 300 303       | (using flux)  | over 95%     |           |
| Thermal Shock               | JEITA ED-4701 | 0°C ~ 100°C   | 100 cycles   | 0/100     |
|                             | 300 307       | 15sec. 15sec.   |              |           |
| Temperature Cycle           | JEITA ED-4701 | -40°C ~ 25°C ~ 100°C ~ 25°C                             | 100 cycles   | 0/100     |
|                             | 100 105       | 30min. 5min. 30min. 5min.                               |              |           |
| Moisture Resistance Cyclic  | JEITA ED-4701 | 25°C ~ 65°C ~ -10°C                                     | 10 cycles    | 0/100     |
|                             | 200 203       | 90%RH 24hrs./1cycle                                     |              |           |
| Terminal Strength           | JEITA ED-4701 | Load 5N (0.5kgf)  | Nonoticeable | 0/100     |
| (bending test)              | 400 401       | $0^{\circ} \sim 90^{\circ} \sim 0^{\circ}$ bend 2 times | damage       |           |
| Terminal Strength           | JEITA ED-4701 | Load 10N (1kgf)   | Nonoticeable | 0/100     |
| (pull test)                 | 400 401       | $10 \pm 1$ sec.   | damage       |           |
| High Temperature Storage    | JEITA ED-4701 | Ta=100°C  | 1000hrs.     | 0/100     |
|                             | 200 201       |   |              |           |
| Temperature Humidity        | JEITA ED-4701 | Ta=60°C, RH=90%   | 1000hrs.     | 0/100     |
| Storage                     | 100 103       |   |              |           |
| Low Temperature Storage     | JEITA ED-4701 | Ta=-40°C  | 1000hrs.     | 0/100     |
|                             | 200 202       |   |              |           |
| Steady State Operating Life |               | Ta=25°C, IF=25mA  | 500hrs.      | 0/100     |
| Steady State Operating Life |               | 60°C, RH=90%, IF=15mA                                   | 500hrs.      | 0/100     |
| of High Humidity Heat       |               |   |              |           |
| Steady State Operating Life |               | Ta=-30°C, IF=20mA                                       | 1000hrs.     | 0/100     |
| of Low Temperature          |               |   |              |           |

# (2) CRITERIA FOR JUDGING THE DAMAGE

|                      |                        |         | Criteria for Judgement |               |  |
|----------------------|------------------------|---------|------------------------|---------------|--|
| Item                 | Symbol Test Conditions |         | Min.                   | Max.          |  |
| Forward Voltage      | VF                     | IF=20mA | -                      | U.S.L.*)× 1.1 |  |
| Optical Power Output | Ро                     | IF=20mA | L.S.L.**)× 0.7         | -             |  |

\*) U.S.L. : Upper Standard Level \*\*) L.S.L. : Lower Standard Level

# 7.CAUTIONS

#### (1) Cautions

• The devices are UV light LEDs. The LED during operation radiates intense UV light, which precautions must be taken to prevent looking directly at the UV light with unaided eyes. Do not look directly into the UV light or look through the optical system. When there is a possibility to receive the reflection of light, protect by using the UV light protective glasses so that light should not catch one's eye directly.

 $\cdot$  Put the caution label on the cardboard box.



### (2) Lead Forming

- $\cdot$  When forming leads, the leads should be bent at a point at least 3mm from the base of the lead. Do not use the base of the leadframe as a fulcrum during lead forming.
- $\cdot$  Lead forming should be done before soldering.
- $\cdot$  Do not apply any bending stress to the base of the lead. The stress to the base may damage the LED's characteristics or it may break the LEDs.
- When mounting the LEDs onto a printed circuit board, the holes on the circuit board should be exactly aligned with the leads of the LEDs. If the LEDs are mounted with stress at the leads, it causes deterioration of the lead and this will degrade the LEDs.
- (3) Storage
  - The LEDs should be stored at 30°C or less and 70%RH or less after being shipped from Nichia and the storage life limits are 3 months. If the LEDs are stored for 3 months or more, they can be stored for a year in a sealed container with a nitrogen atmosphere and moisture absorbent material.
  - Nichia LED leads are comprised of a gold plated Iron alloy. The gold surface may be affected by environments which contain corrosive gases and so on. Please avoid conditions which may cause the LED to corrode, tarnish or discolor. This corrosion or discoloration may cause difficulty during soldering operations. It is recommended that the LEDs be used as soon as possible.
- $\cdot$  Please avoid rapid transitions in ambient temperature, especially, in high humidity environments where condensation can occur.

# (4) Static Electricity

- $\cdot$  Static electricity or surge voltage damages the LEDs.
- It is recommended that a wrist band or an anti-electrostatic glove be used when handling the LEDs.
- All devices, equipment and machinery must be properly grounded. It is recommended that measures be taken against surge voltage to the equipment that mounts LEDs.
- When inspecting the final products in which LEDs were assembled, it is recommended to check whether the assembled LEDs are damaged by static electricity or not. It is easy to find static-damaged LEDs by a light-on test or a VF test at a lower current (below 1mA is recommended). The LEDs should be used the light detector etc. when testing the light-on. Do not stare into the LEDs when testing.
- Damaged LEDs will show some unusual characteristics such as the forward voltage becomes lower, or the LEDs do not light at the low current.

Criteria : (VF > 2.0V at IF=0.5mA)

#### (5) Soldering Conditions

 $\cdot$  Solder the LED no closer than 3mm from the base of the lead.

· Recommended soldering conditions

| Dip Soldering           |                             | Soldering      |                              |  |
|-------------------------|-----------------------------|----------------|------------------------------|--|
| Pre-Heat                | 120°C Max.                  | Temperature    | 350°C Max.                   |  |
| Pre-Heat Time           | 60 seconds Max.             | Soldering Time | 3 seconds Max.               |  |
| Solder Bath             | 260°C Max.                  | Position       | No closer than 3 mm from the |  |
| Temperature             |                             |                | base of the lead.            |  |
| Dipping Time            | 10 seconds Max.             |                |                              |  |
| <b>Dipping Position</b> | No lower than 3 mm from the |                |                              |  |
|                         | base of the lead.           |                |                              |  |

- $\cdot$  Do not apply any stress to the lead particularly when heated.
- $\cdot$  The LEDs must not be repositioned after soldering.
- After soldering the LEDs, the lead should be protected from mechanical shock or vibration until the LEDs return to room temperature.
- Direct soldering onto a PC board should be avoided. Mechanical stress to the glass may be caused from warping of the PC board or from the clinching and cutting of the leads. When it is absolutely necessary, the LEDs may be mounted in this fashion but the User will assume responsibility for any problems. Direct soldering should only be done after testing has confirmed that no damage, such as wire bond failure or glass deterioration, will occur. Nichia's LEDs should not be soldered directly to double sided PC boards because the heat will deteriorate the glass.
- $\cdot$  When it is necessary to clamp the LEDs to prevent soldering failure, it is important to minimize the mechanical stress on the LEDs.
- $\cdot$  Cut the LED leads at room temperature. Cutting the leads at high temperatures may cause failure of the LEDs.
- (6) Heat Generation
  - Thermal design of the end product is of paramount importance. Please consider the heat generation of the LED when making the system design. The coefficient of temperature increase per input electric power is affected by the thermal resistance of the circuit board and density of LED placement on the board, as well as other components. It is necessary to avoid intense heat generation and operate within the maximum ratings given in this specification.

 $\cdot$  The operating current should be decided after considering the ambient maximum temperature of LEDs.

- (7) Cleaning
- It is recommended that isopropyl alcohol be used as a solvent for cleaning the LEDs. When using other solvents, it should be confirmed beforehand whether the solvents will dissolve the resin or not. Freon solvents should not be used to clean the LEDs because of worldwide regulations.
- Do not clean the LEDs by the ultrasonic. When it is absolutely necessary, the influence of ultrasonic cleaning on the LEDs depends on factors such as ultrasonic power and the assembled condition. Before cleaning, a pre-test should be done to confirm whether any damage to the LEDs will occur.

#### (8) Safety Guideline for Human Eyes

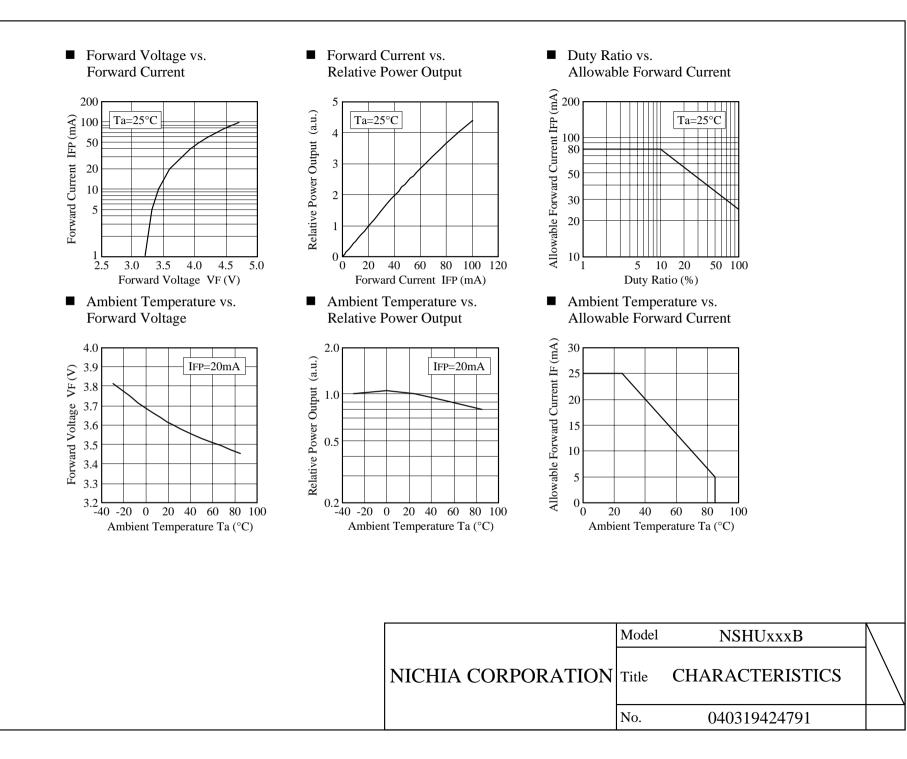
In 1993, the International Electric Committee (IEC) issued a standard concerning laser product safety (IEC 825-1). Since then, this standard has been applied for diffused light sources (LEDs) as well as lasers. In 1998 IEC 60825-1 Edition 1.1 evaluated the magnitude of the light source. In 2001 IEC 60825-1 Amendment 2 converted the laser class into 7 classes for end products. Components are excluded from this system. Products which contain visible LEDs are now classified as class 1. Products containing UV LEDs are class 1M. Products containing LEDs can be classified as class 2 in cases where viewing angles are narrow, optical manipulation intensifies the light, and/or the energy emitted is high. For these systems it is recommended to avoid long term exposure. It is also recommended to follow the IEC regulations regarding safety and labeling of products.

#### (9) Others

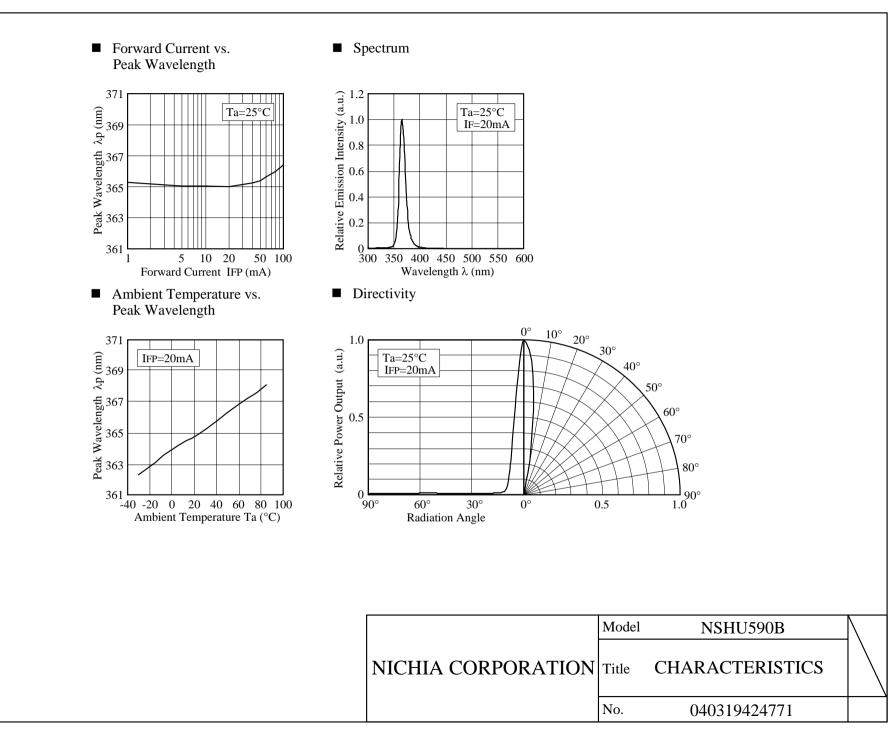
- The LEDs described in this brochure are intended to be used for ordinary electronic equipment (such as office equipment, communications equipment, measurement instruments and household appliances). Consult Nichia's sales staff in advance for information on the applications in which exceptional quality and reliability are required, particularly when the failure or malfunction of the LEDs may directly jeopardize life or health (such as for airplanes, aerospace, submersible repeaters, nuclear reactor control systems, automobiles, traffic control equipment, life support systems and safety devices).
- User shall not reverse engineer by disassembling or analysis of the LEDs without having the prior written consent of Nichia. When defective LEDs are found, User shall inform to Nichia directly before disassembling or analysis.

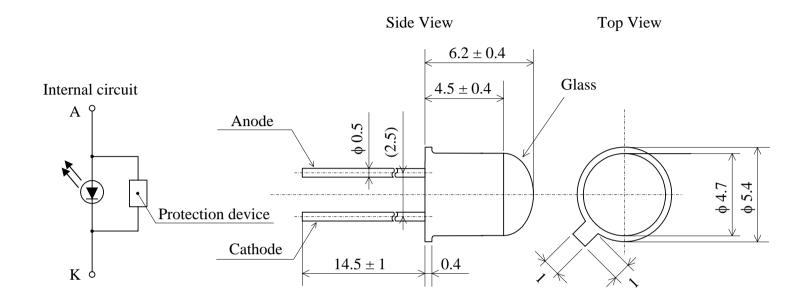
 $\cdot$  The formal specifications must be exchanged and signed by both parties before large volume purchase begins.

· The appearance and specifications of the product may be modified for improvement without notice.



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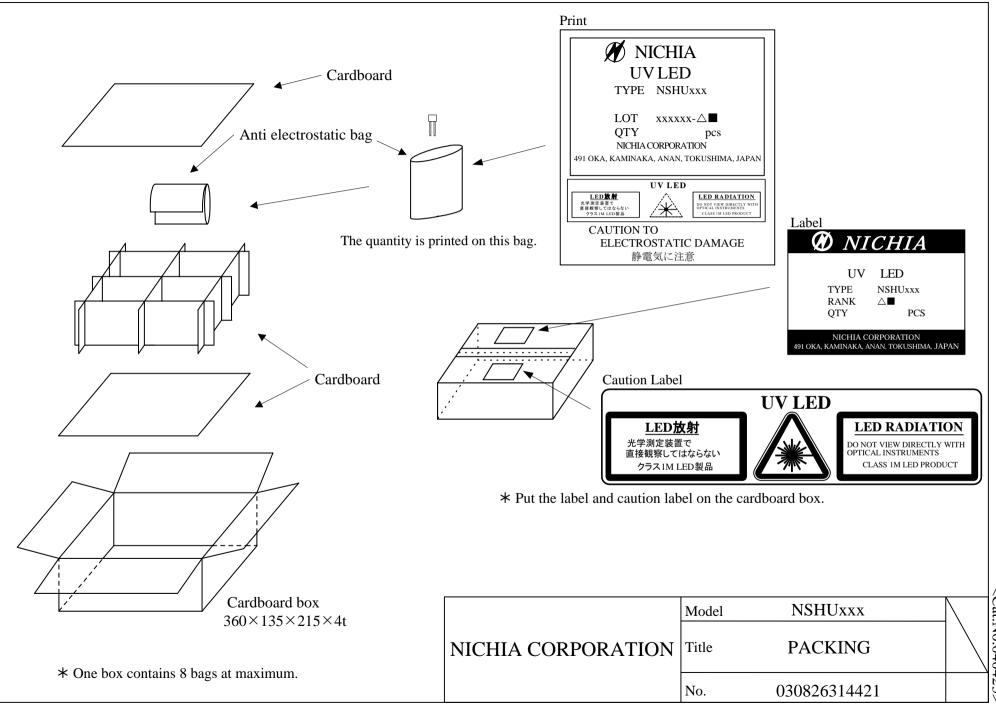


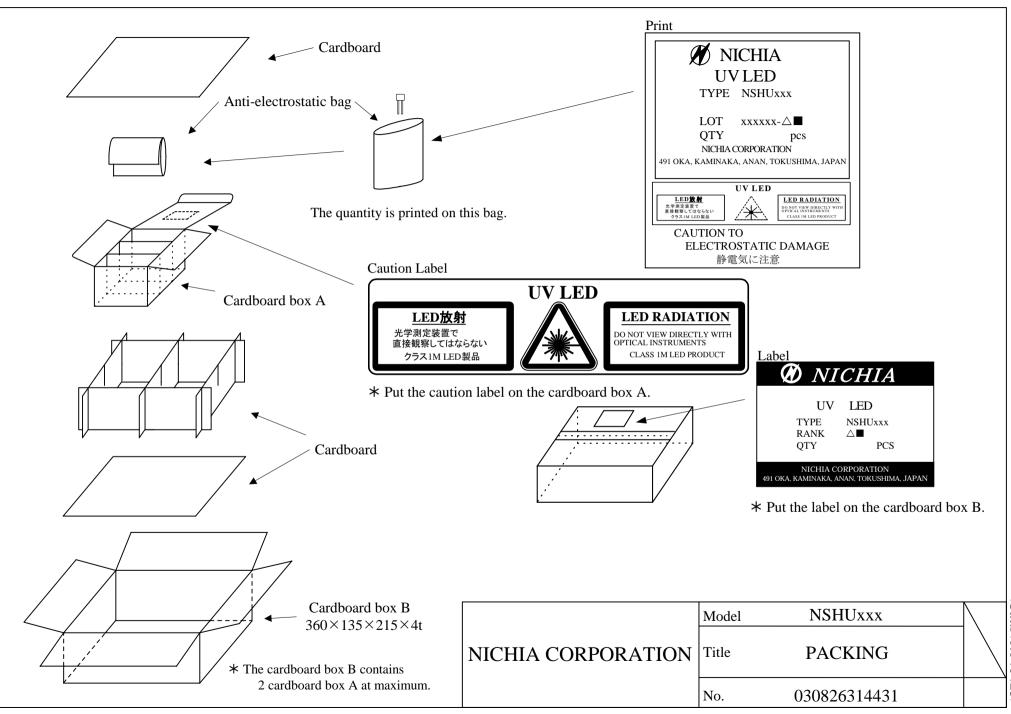
\* NSHU590B has a protection device built in as a protection circuit against static electricity.

| ITEM  | MATERIALS             |  |  |
|-------|-----------------------|--|--|
| GLASS | Hard Glass            |  |  |
| CAP   | Ni Plating Iron Alloy |  |  |
| LEAD  | Au Plating Iron Alloy |  |  |

| NICHIA CORPORATION | Model | NSHU590B           | Unit         |
|--------------------|-------|--------------------|--------------|
|                    | Title | OUTLINE DIMENSIONS | 5/1<br>Scale |
|                    | No.   | 040317424431       | Allow ±0.2   |

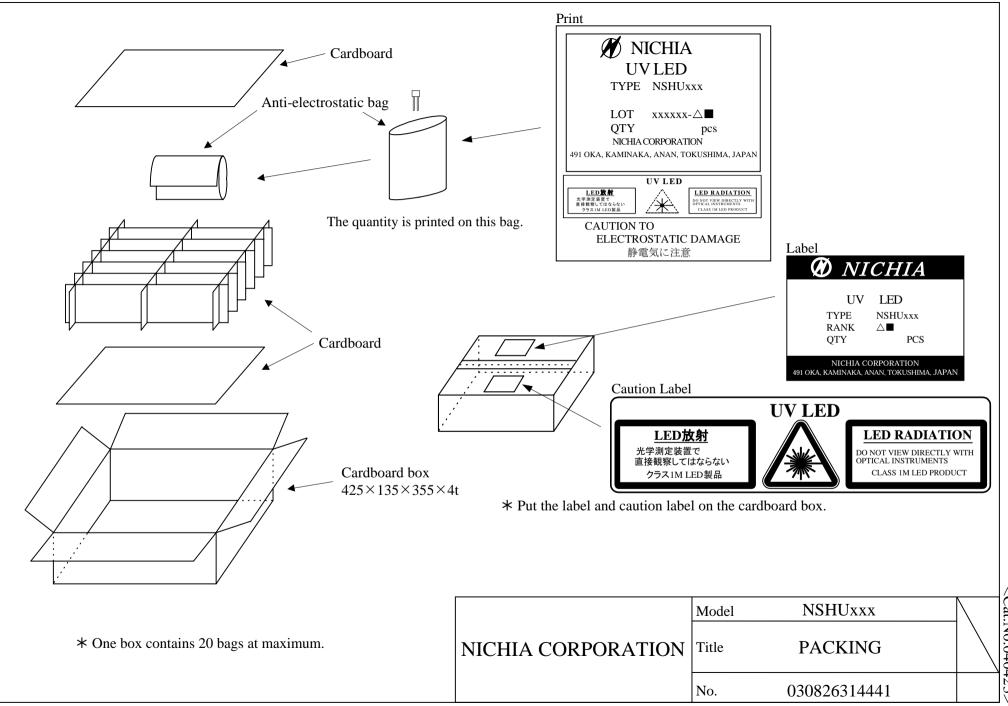
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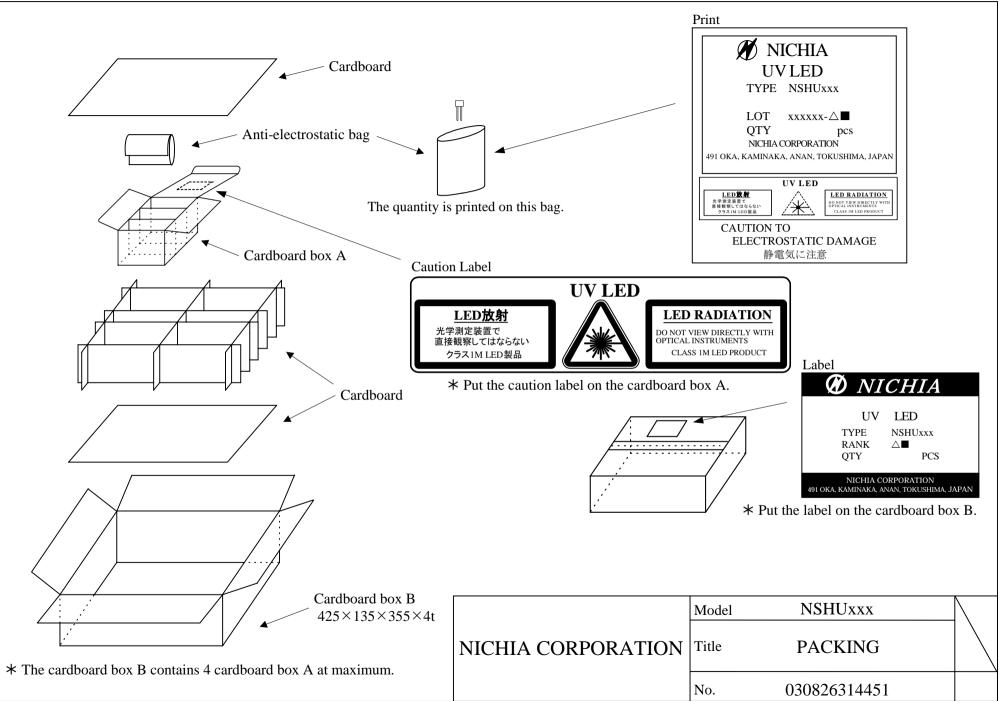




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Nichia STSE-CH4023A <Cat.No.040423>





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